



Material Content Data Sheet



Sales Product Name		BSP762T		Issued		22. January 2018		
MA#		MA001221710						
Package		PG-DSO-8-24		Weight*		83.36 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.265	2.72	2.72	27177	27177
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		108	
	non noble metal	zinc	7440-66-6	0.036	0.04		430	
	non noble metal	iron	7439-89-6	0.717	0.86		8603	
wire	non noble metal	copper	7440-50-8	29.121	34.93	35.84	349335	358476
	noble metal	gold	7440-57-5	0.444	0.53	0.53	5330	5330
	plastics	epoxy resin	-	4.466	5.36		53569	
encapsulation	inorganic material	silicondioxide	60676-86-0	43.976	52.75		527538	
	organic material	carbon black	1333-86-4	0.097	0.12	58.23	1165	582272
leadfinish	non noble metal	tin	7440-31-5	0.814	0.98	0.98	9763	9763
plating	noble metal	silver	7440-22-4	0.650	0.78	0.78	7800	7800
glue	noble metal	silver	7440-22-4	0.631	0.76		7575	
	plastics	epoxy resin	-	0.134	0.16	0.92	1607	9182
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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